

TC7PCI3212MT, TC7PCI3215MT

1. Functional Description

- 2 Differential Channel, 2:1 multiplexer/demultiplexer switch for PCI Express Gen 3

2. General

The TC7PCI3212MT and TC7PCI3215MT are 2 differential channel, 1-2 multiplexer/demultiplexer for PCI Express Gen3 (8Gbps), or other high-speed interface applications.

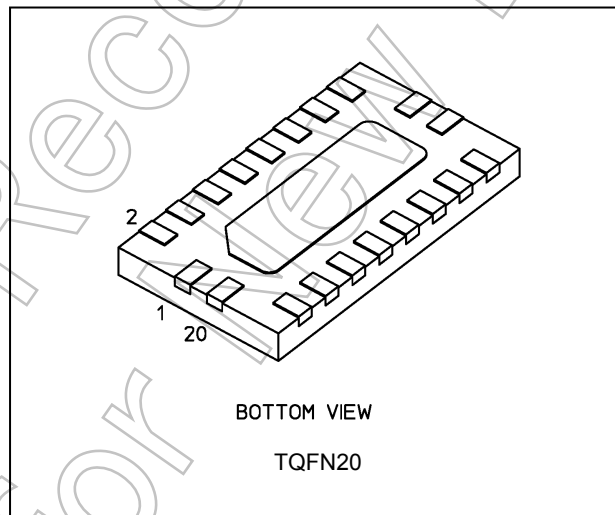
The A_n^+/A_n^- inputs is connected to the B_n^+/B_n^- or C_n^+/C_n^- outputs determined by the combination both the select input (SEL) and output enable ($\overline{OE}$). When the output enable ($\overline{OE}$) input is held high-level, the switches are open (high-impedance state) with regardless the state of select inputs and reducing consumption current.

All inputs are equipped with protection circuits against static discharge.

3. Features

- (1) Operating voltage: $V_{CC} = 3.0$ to 3.6 V
- (2) Switch terminal ON-capacitance: $C_{I/O} = 1.5$ pF Switch On (typ.) @ $V_{CC} = 3.3$ V
- (3) ON resistance: $R_{ON} = 7.5$ Ω (typ.) @ $V_{CC} = 3.0$ V, $V_{IS} = 0$ V
- (4) -3dB Bandwidth: $BW = 11.5$ GHz (typ.) @ $V_{CC} = 3.3$ V
- (5) Insertion Loss: $DDIL = -1$ dB (typ.) @ $V_{CC} = 3.3$ V, $f = 4$ GHz
- (6) Off Isolation: $DDOIRR = -20$ dB (typ.) @ $V_{CC} = 3.3$ V, $f = 4$ GHz
- (7) Crosstalk: $DDNEXT = -40$ dB (typ.) @ $V_{CC} = 3.3$ V, $f = 4$ GHz
- (8) Package: TQFN20

4. Packaging

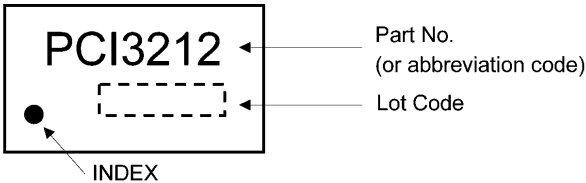


Start of commercial production

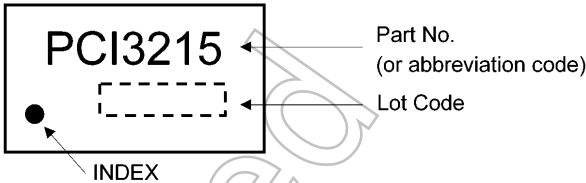
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5. Marking

TC7PCI3212MT

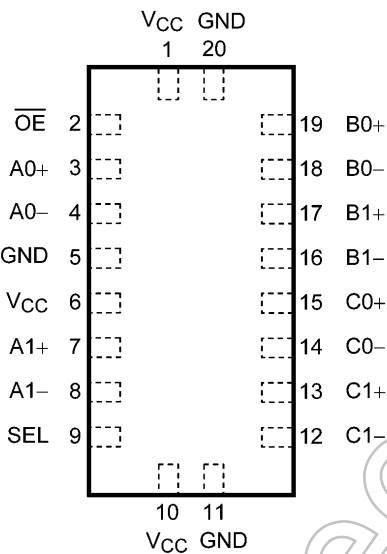


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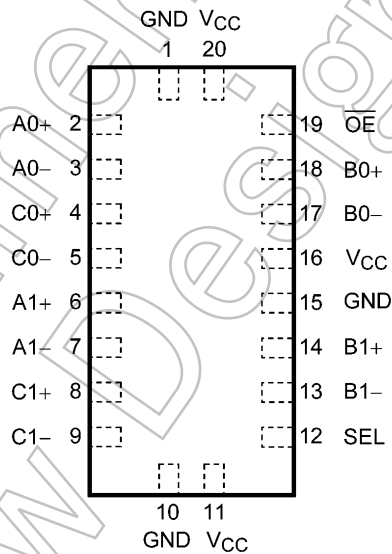


6. Pin Assignment

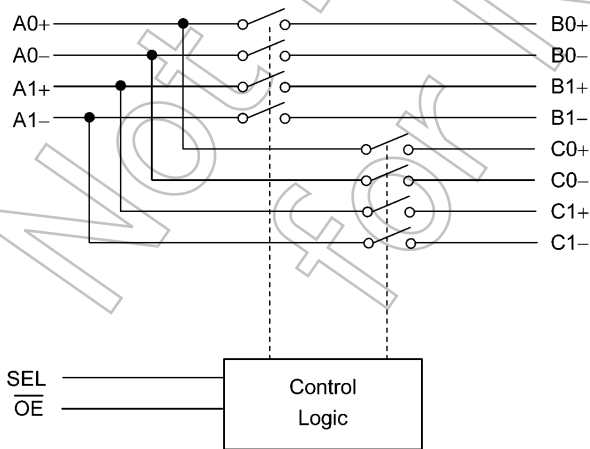
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TC7PCI3215MT



7. Block Diagram



8. Principle of Operation

8.1. Truth Table

Inputs OE	Inputs SEL	Function	Function
L	L	An+ port = Bn+ port, An- port = Bn- port	(n=0,1)
L	H	An+ port = Cn+ port, An- port = Cn- port	(n=0,1)
H	—	An, Bn, Cn port Disconnect	(n=0,1)

—: Don't care.

9. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Rating	Unit
Supply voltage	V_{CC}	-0.5 to 4.6	V
Input voltage ($\overline{OE}$, SEL)	V_{IN}	-0.5 to 4.6	V
Switch I/O voltage	V_S	-0.5 to $V_{CC}+0.5$	V
Switch I/O current	I_S	50	mA
Power dissipation	P_D	500	mW
V_{CC} /ground current	I_{CC}/I_{GND}	± 50	mA
Storage temperature	T_{stg}	-55 to 125	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

10. Operating Ranges (Note)

Characteristics	Symbol	Rating	Unit
Supply voltage	V_{CC}	3.0 to 3.6	V
Input voltage ($\overline{OE}$, SEL)	V_{IN}	0 to 3.6	V
Signal pins differential voltage.	$V_{I/O(Diff)}$	0 to 1.8	V
Signal pins common mode voltage.	$V_{I/O(Com)}$	0 to 2.0	V
Operating temperature	T_{opr}	-40 to 85	°C
Input rise and fall times	dt/dv	0 to 10	ns/V

Note: The operating ranges must be maintained to ensure the normal operation of the device.

Unused control inputs must be tied to either V_{CC} or GND.

11. Electrical Characteristics

11.1. DC Characteristics (Note) (Unless otherwise specified, $T_a = -40$ to $85\text{ }^{\circ}\text{C}$)

Characteristics	Symbol	Note	Test Condition	V_{CC} (V)	Min	Typ.	Max	Unit
High-level input voltage ($\overline{OE}$, SEL)	V_{IH}		—	3.0 to 3.6	$0.65 \times V_{CC}$	—	—	V
Low-level input voltage ($\overline{OE}$, SEL)	V_{IL}		—	3.0 to 3.6	—	—	$0.35 \times V_{CC}$	V
Input leakage current ($\overline{OE}$, SEL)	I_{IN}		$V_{IN} = 0$ to 3.6 V	3.0 to 3.6	—	—	± 1	μA
Switch OFF-state leakage current	I_{SZ}		$V_{IS} = 0$ to V_{CC} , $\overline{OE} = V_{CC}$	3.0 to 3.6	—	—	± 1	μA
ON-resistance	R_{ON}	(Note 1)	$V_{IS} = 0$ V, $I_{IS} = 30$ mA	3.0	—	7.5	11.5	Ω
	R_{ON}	(Note 1)	$V_{IS} = 1.2$ V, $I_{IS} = 30$ mA	3.0	—	8.5	13.5	Ω
Difference of ON-resistance between switches (bit to bit)	ΔR_{ON}	(Note 1)	$V_{IS} = 0$ V, 1.2 V, $I_{IS} = 15$ mA	3.0	—	0.1	—	Ω
ON-resistance flatness	$R_{ON(\text{flat})}$	(Note 1)	$V_{IS} = 0$ V to 1.2 V, $I_{IS} = 15$ mA	3.0	—	1	—	Ω
Quiescent supply current	I_{CC}		$V_{IN} = V_{CC}$ or GND, $\overline{OE} = V_{CC}$	3.6	—	—	1	μA
Quiescent supply current	I_{CC}		$V_{IN} = V_{CC}$ or GND, $\overline{OE} = \text{GND}$	3.6	—	200	500	μA

Note : All typical values are at $T_a = 25\text{ }^{\circ}\text{C}$.

Note 1: ON-resistance is measured by measuring the voltage drop across the switch at the indicated current.

11.2. AC Characteristics (Note) (Unless otherwise specified, $T_a = -40$ to 85 °C)

Characteristics	Symbol	Note	Test Condition	V_{CC} (V)	Min	Typ.	Max	Unit
Propagation delay time	t_{PLH}/t_{PHL}	(Note 1)	$C_L = 5$ pF See Fig. 12.1	3.3 ± 0.3	—	0.1	—	ns
Turn-ON time (SEL to Output)	t_{on}		$R_L = 50 \Omega$, $C_L = 5$ pF See Fig. 12.2	3.3 ± 0.3	—	10	15	ns
Turn-ON time ($\overline{OE}$ to Output)	t_{on}		$R_L = 50 \Omega$, $C_L = 5$ pF See Fig. 12.2	3.3 ± 0.3	—	37	50	μ s
Turn-OFF time (SEL to Output)	t_{off}		$R_L = 50 \Omega$, $C_L = 5$ pF See Fig. 12.2	3.3 ± 0.3	—	3.5	5	ns
Turn-OFF time ($\overline{OE}$ to Output)	t_{off}		$R_L = 50 \Omega$, $C_L = 5$ pF See Fig. 12.2	3.3 ± 0.3	—	5	6.5	ns
Break before make	TBBM		$R_L = 50 \Omega$, $C_L = 5$ pF See Fig. 12.3	3.3 ± 0.3	3	—	9	ns
Output skew (bit to bit)	$t_{SK(b)}$	(Note 1)	$C_L = 5$ pF See Fig. 12.4	3.3 ± 0.3	—	5	—	ps
Output skew (channel to channel)	$t_{SK(CH)}$	(Note 1)	$C_L = 5$ pF See Fig. 12.5	3.3 ± 0.3	—	10	—	ps
Differential OFF isolation	DDOIRR	(Note 1)	$R_T = 50 \Omega$, $f = 4$ GHz See Fig. 12.6	3.3 ± 0.3	—	-20	—	dB
Differential Near-end crosstalk	DDNEXT	(Note 1)	$R_T = 50 \Omega$, $f = 4$ GHz See Fig. 12.7	3.3 ± 0.3	—	-40	—	dB
Differential return loss	DDRL	(Note 1)	$R_T = 50 \Omega$, $f = 4$ GHz See Fig. 12.8	3.3 ± 0.3	—	-20	—	dB
Differential insertion loss	DDIL	(Note 1)	$R_T = 50 \Omega$, $f = 4$ GHz See Fig. 12.8	3.3 ± 0.3	—	-1	—	dB
-3dB Bandwidth	BW	(Note 1)	$R_T = 50 \Omega$, $C_L = 0$ pF See Fig. 12.8	3.3 ± 0.3	—	11.5	—	GHz

Note : All typical values are at $T_a = 25$ °C.

Note 1: This parameter is guaranteed by design.

11.3. Capacitive Characteristics (Note) (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Note	Test Condition	V_{CC} (V)	Typ.	Unit
Input capacitance ($\overline{OE}$, SEL)	C_{IN}		$V_{IN} = 0$ V	3.3	3	pF
Switch terminal OFF-capacitance ($An+$, $An-$)	$C_{I/O}$		$\overline{OE} = V_{CC}$, $V_{IS} = 0$ V	3.3	0.8	pF
Switch terminal OFF-capacitance ($Bn+$, $Bn-$, $Cn+$, $Cn-$)			$\overline{OE} = V_{CC}$, $V_{IS} = 0$ V	3.3	0.5	pF
Switch terminal ON-capacitance	$C_{I/O}$		$\overline{OE} = GND$, $V_{IS} = 0$ V	3.3	1.5	pF

Note: Parameter guaranteed by design.

12. AC Electrical Test Circuit (Fig)

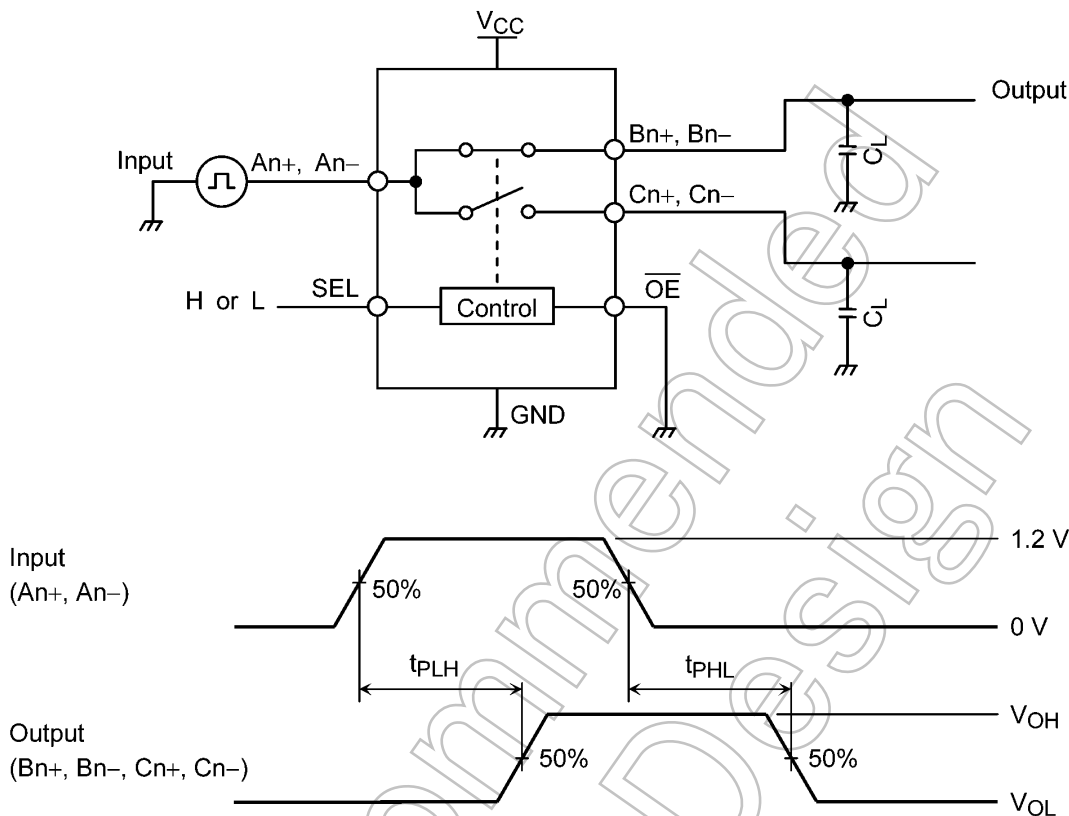
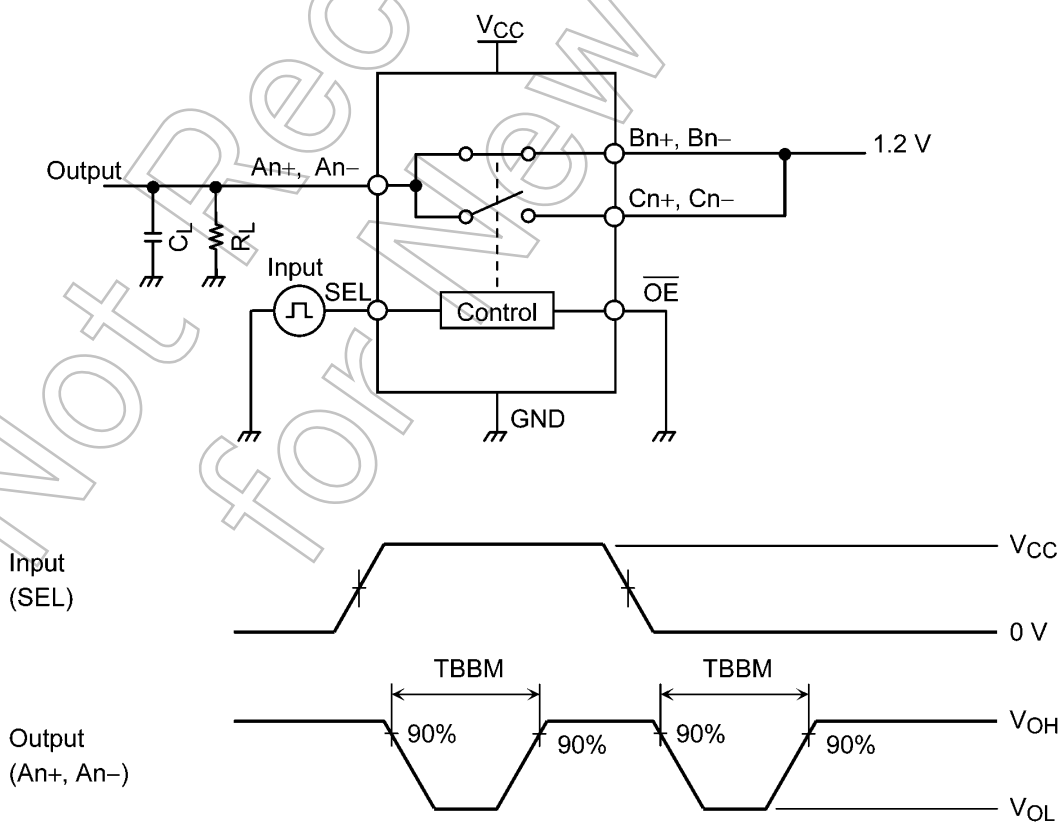
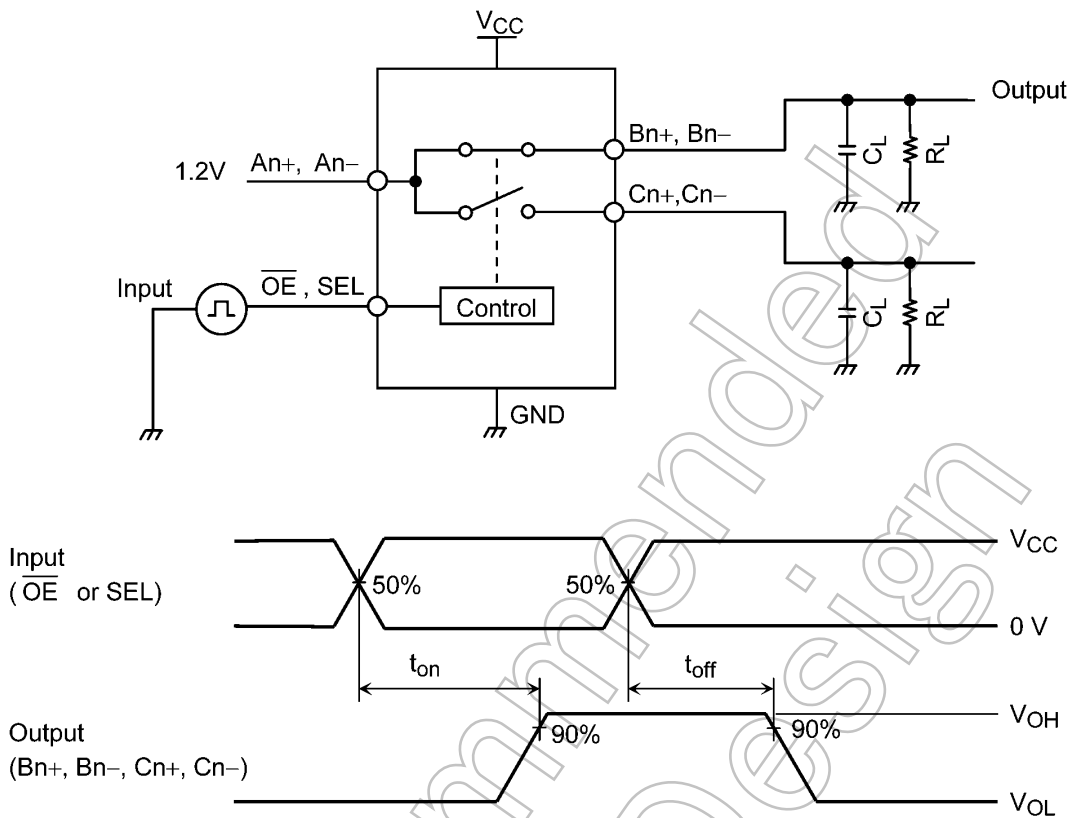


Fig. 12.1 Propagation delay time



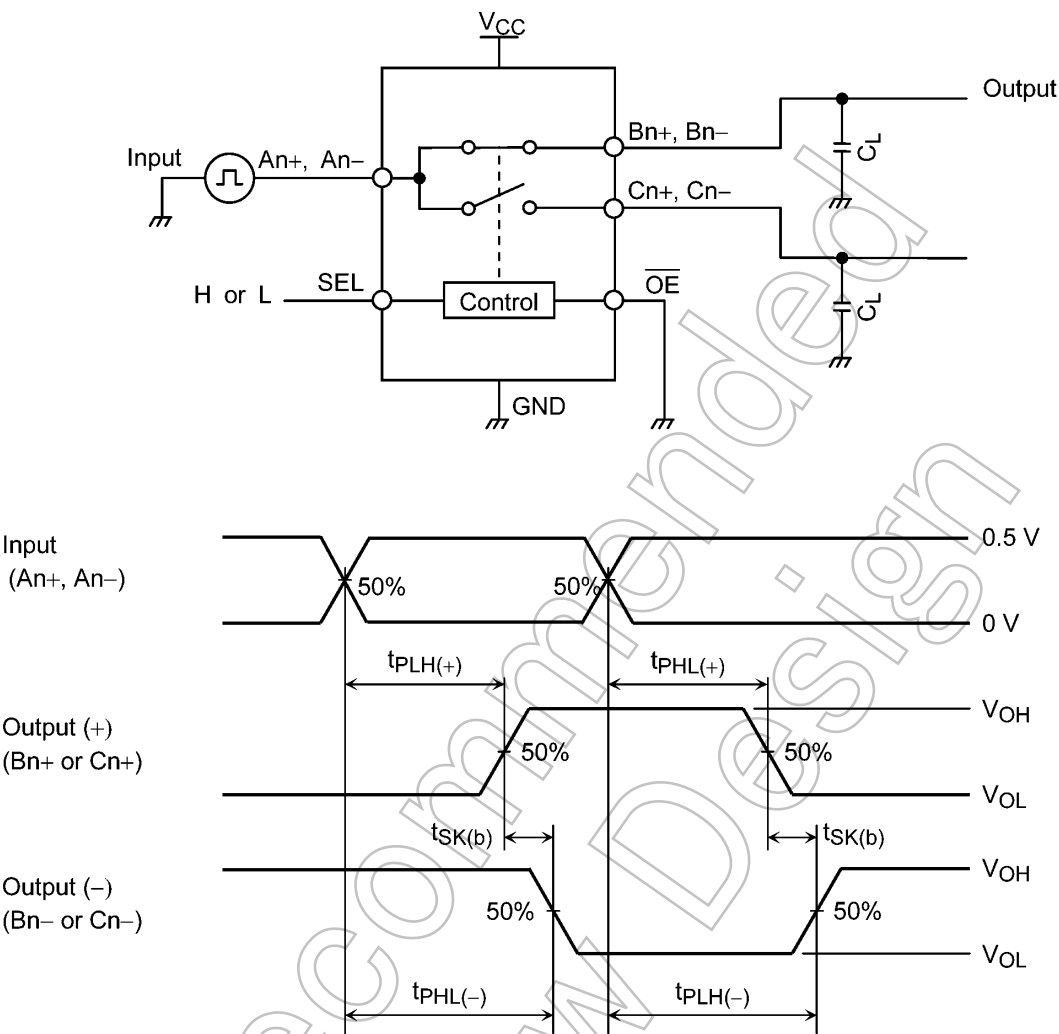


Fig. 12.4 Output skew (bit to bit)

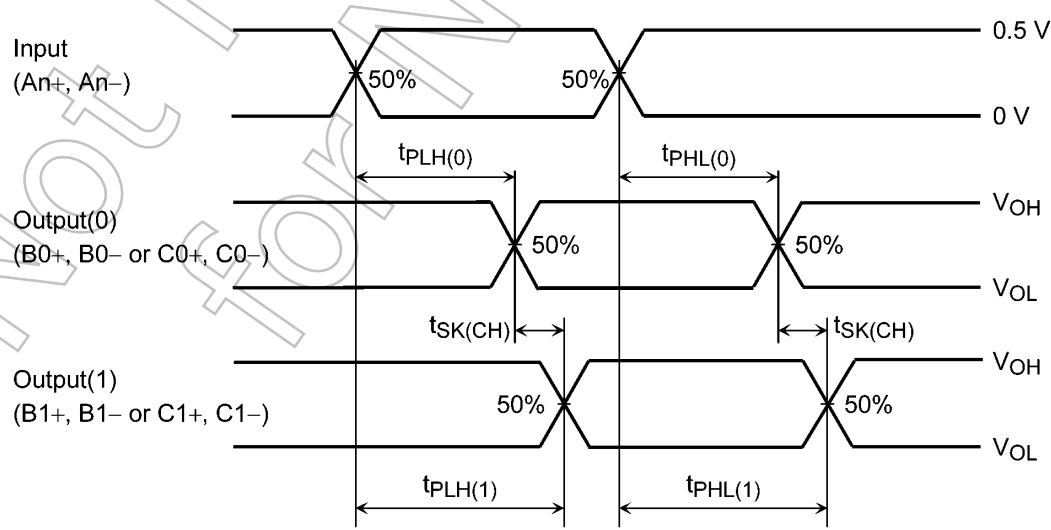
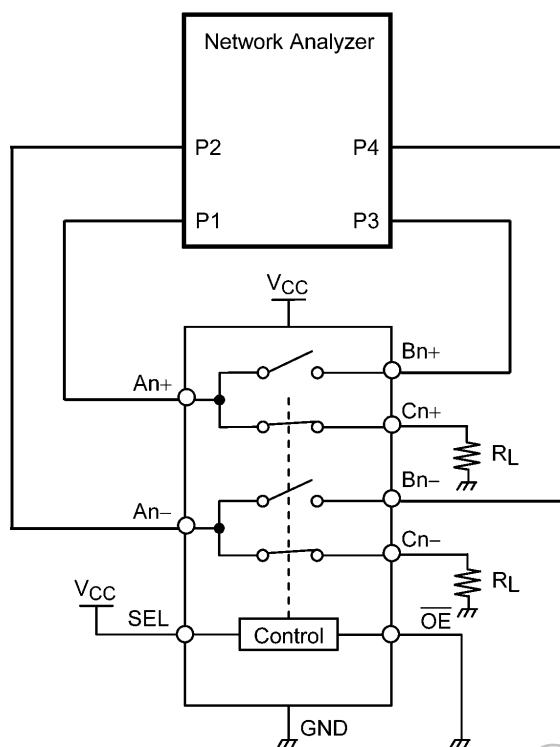


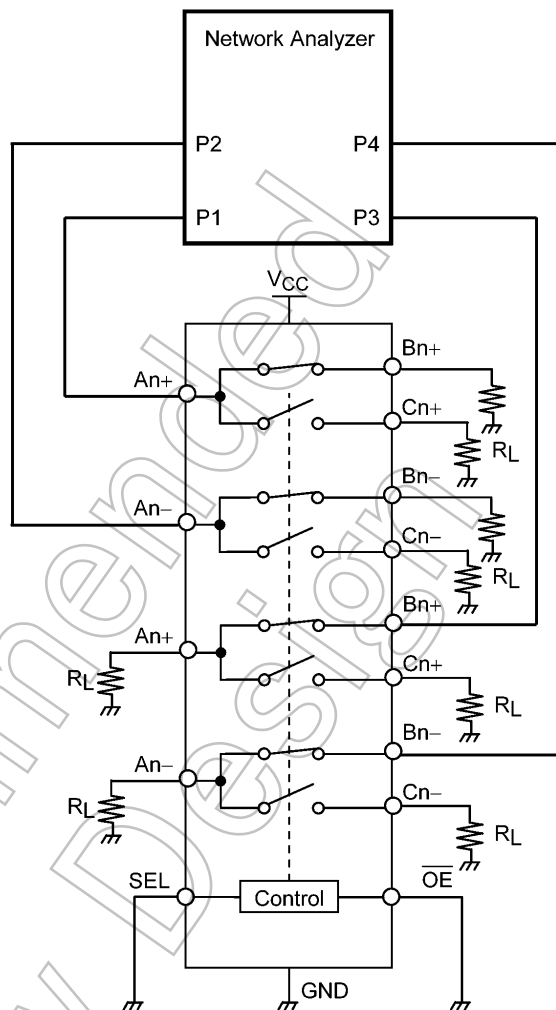
Fig. 12.5 Output skew (channel to channel)



$R_L = 50\ \Omega$

All unused ports are connected to GND through $50\ \Omega$ pull-down resistors.

Fig. 12.6 Differential OFF isolation



$R_L = 50\ \Omega$

All unused ports are connected to GND through $50\ \Omega$ pull-down resistors.

Fig. 12.7 Differential Near-end crosstalk

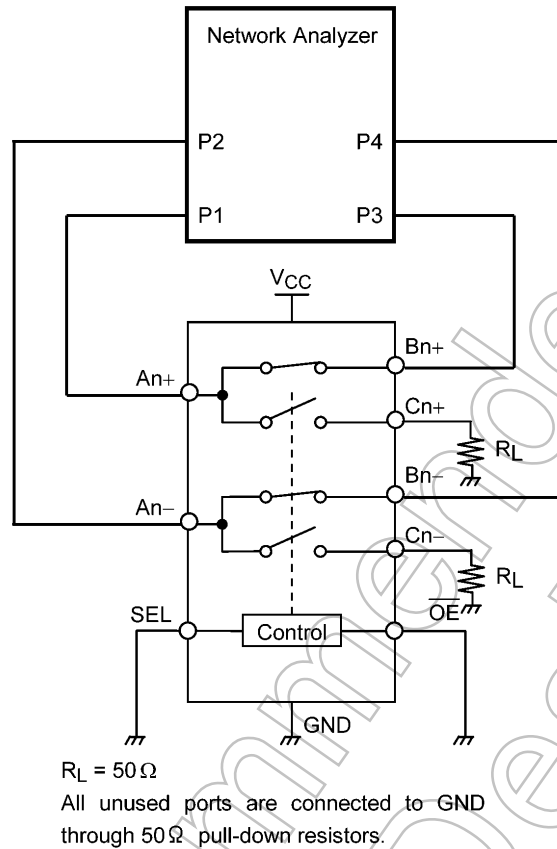
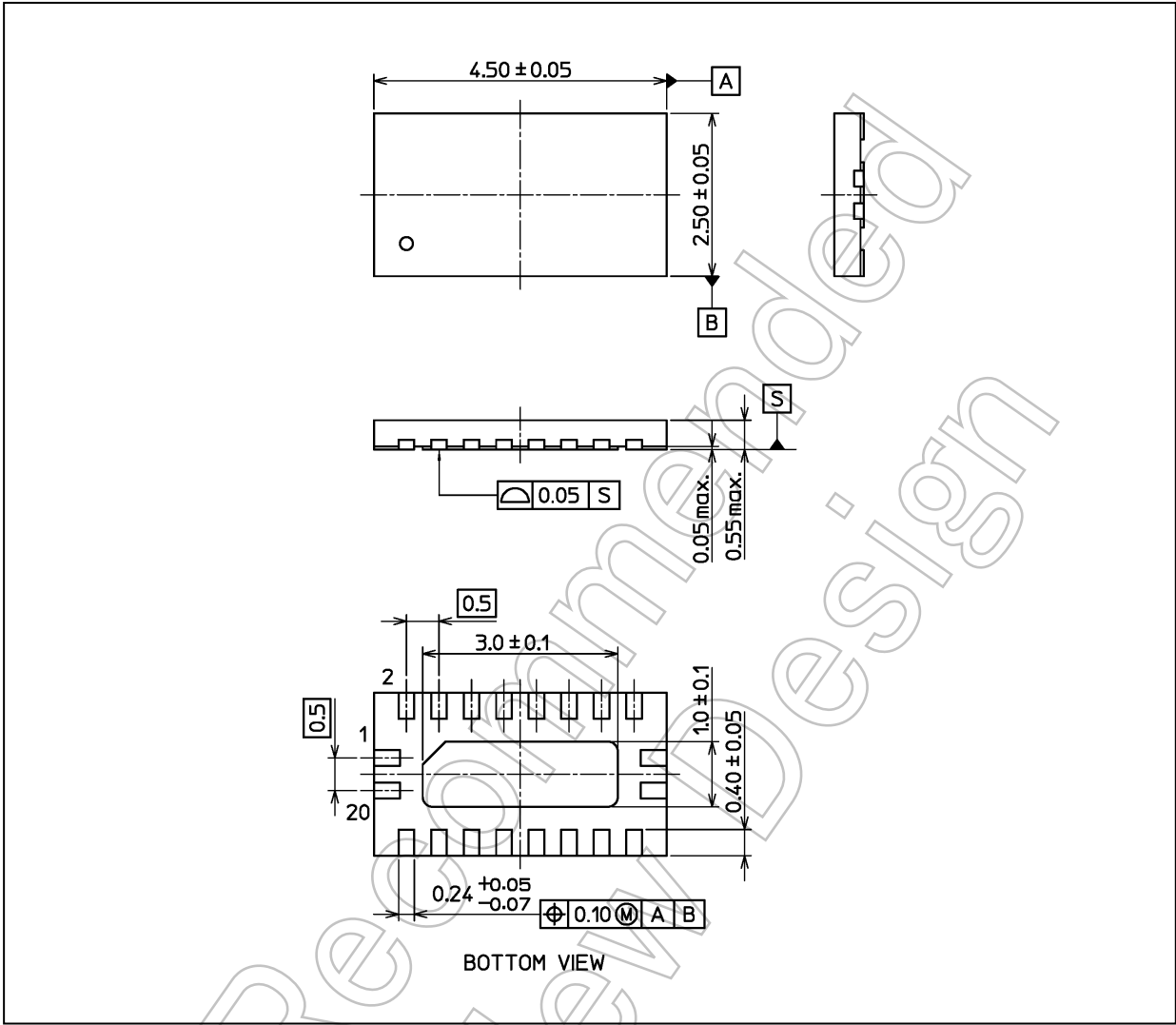


Fig. 12.8 Differential return loss, Differential insertion loss, -3dB Bandwidth

Package Dimensions

Unit: mm



Weight: 0.017 g (typ.)

Package Name(s)
Nickname: TQFN20

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